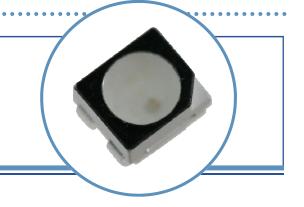
## Full Color PLCC4 LED



#### **OVSARGB4R8**

- Surface mount device packaged in 8 mm tape on 7" diameter reel
- Compatible with automatic placement equipment
- Compatible with infrared and vapor phase reflow solder
- Dimensions: 3.5 x 2.8 x 1.9 mm
- 120° viewing angle

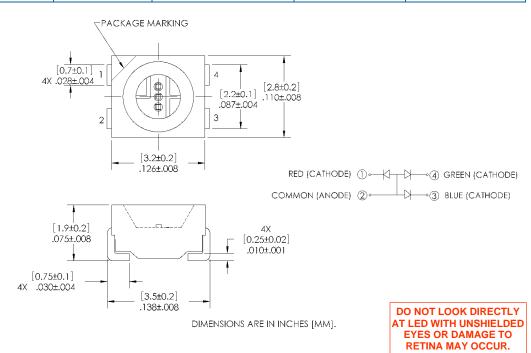


The **OVSARGB4R8** provides full color light output from a single package, 3-die design. This surface mount package is an efficient solution in modular applications that require uniform brightness and color-on-demand. Light output is optimized by an interior reflector and the wide viewing angle adds flexibility for applications ranging from hand-held appliances to automotive interiors.

#### **Applications**

- RGB full-color indoor and outdoor displays
- Backlighting
- · Coupling into light guides
- Automotive interiors
- · Entertainment equipment

Dort Number		Long Color			
Part Number	Type	Material	Emitted Color	Intensity Typ. mcd	Lens Color
OVSARGB4R8	R	AllnGaP	Red	550	
	G	InGaN	Green	850	Diffused
	В	InGaN	Blue	320	







## Absolute Maximum Ratings $T_A = 25^{\circ} C$ unless otherwise noted

DADAMETED		RATING		
PARAMETER	R	G	В	UNIT
Storage Temperature		-40 ~ +100		C
Operating Temperature		-40 ~ +100		C
Reverse Voltage		5		V
Continuous Forward Current (1 chip on)	50	25	25	mA
Peak Forward Current (10% Duty Cycle, PW ≤ 100 µsec, 1 chip on)	200	100	100	mA
Power Dissipation	130	100	100	mW
Junction Temperature	110	110	110	S.
Junction/ambient (1 chip on)	450	400	450	.c\M
Junction/ambient (3 chips on)	650	580	680	€/M
Junction/solder point (1 chip on)	300	280	300	€/W
Junction/solder point (3 chips on)	450	430	480	€/W
Electrostatic Discharge Classification (JEDEC-JESD22-A114F)		<u> </u>	•	Class 1C
Moisture Sensitivity Level (IPC/JEDEC J-STD-020C)			5a / 24 Hrs	

### **Electrical Characteristics**

 $T_A = 25^{\circ} \, C$  unless otherwise noted

SYMBOL	DADAMETED	VALUES				LINIT	CONDITIONS
SYMBOL	PARAMETER		R	G	В	UNIT	CONDITIONS
	Luminous Intensity	Min	355	560	180	mcd	I <sub>F</sub> = 20 mA
I <sub>V</sub>		Тур	550	850	320		
V <sub>F</sub>	Forward Voltage	Тур	2.0	3.2	3.2	V	I <sub>F</sub> = 20 mA
		Max	2.6	4.0	4.0		
I <sub>R</sub>	Reverse Current (max)		10	10	10	μΑ	V <sub>R</sub> = 5 V
$\lambda_{D}$	Dominant Wavelength		619-624	520–540	460–480	nm	I <sub>F</sub> = 20 mA
$\lambda_{P}$	Wavelength at Peak Emission		630	527	470	nm	I <sub>F</sub> = 20 mA
2 ⊝½	50% Power Angle		120	120	120	deg	I <sub>F</sub> = 20 mA
Δλ	Spectral Radiation Bandwidth		24	38	28	nm	I <sub>F</sub> = 20 mA



### Standard Bins

LEDs are sorted to luminous intensity ( $I_V$ ) and dominant wavelength (nm) bins shown. Each reel consists of a single intensity bin and a single color bin. Orders are filled using all intensity and color bins listed in the following tables. Optek will not accept orders for single intensity bins or single color bins.

#### Luminous Intensity (I<sub>V</sub>) @ 20mA

	RED	
Code	Min (mcd)	Max (mcd)
Н	355	450
J	450	560
K	560	710

	GREEN	
Code	Min (mcd)	Max (mcd)
K	560	710
М	710	900
N	900	1120

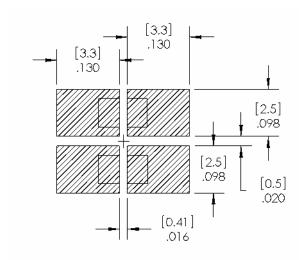
	BLUE	
Code	Min (mcd)	Max (mcd)
Е	180	224
F	224	280
G	280	355

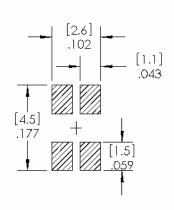
#### Dominant Wavelength (nm)

	RED	
Code	Min (nm)	Max (nm)
RB	619	624

	GREEN	
Code	Min (nm)	Max (nm)
G7	520	525
G8	525	530
G9	530	535
Ga	535	540

	BLUE	
Code	Min (nm)	Max (nm)
В3	460	465
B4	465	470
B5	470	475



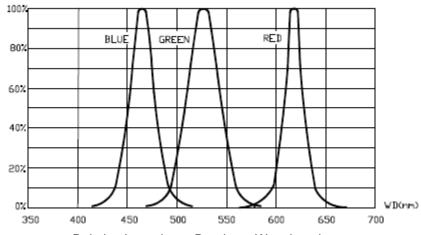


RECOMMENDED SOLDER PASTE PATTERN

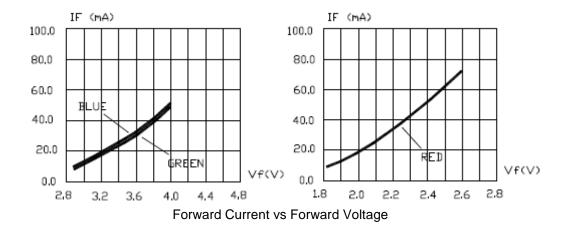
RECOMMENDED COPPER PATTERN

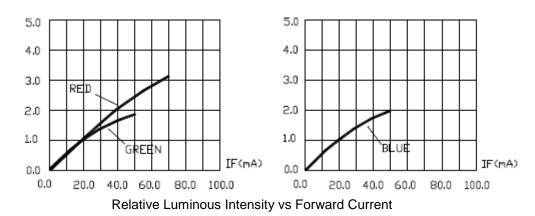


### Typical Electro-Optical Characteristics Curves



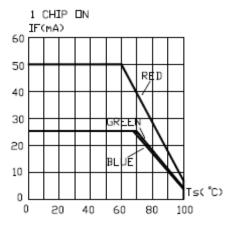
Relative Intensity vs Dominant Wavelength

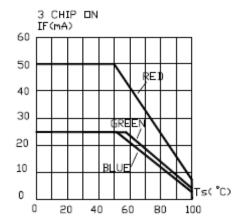




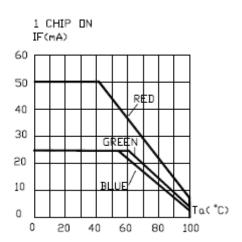


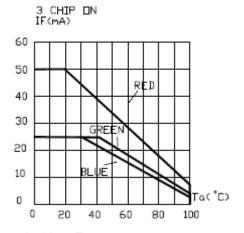
### Typical Electro-Optical Characteristics Curves



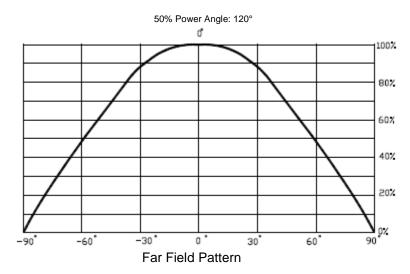


Maximum Forward DC Current vs Solder Point Temperature





Maximum Forward DC Current vs Ambient Temperature

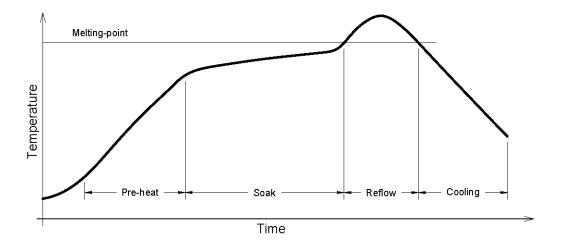




#### Reflow Solder Profile

### Manual soldering by soldering iron:

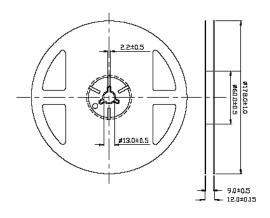
- The use of a soldering iron of less than 25 W is recommended. The temperature of the iron must be kept at below 315℃ with soldering time within 2 seconds
- The epoxy resin of the SMD LED should not contact the tip of the soldering iron.
- No mechanical stress should be exerted on the resin portion of the SMD LED during soldering.
- Handling of the SMD LED should be done when the package has been cooled down to below 40℃ or less. This is to prevent LED failures due to thermal-mechanical stress during handling.
- The temperature (top surface of the SMD LED) profile is as below:



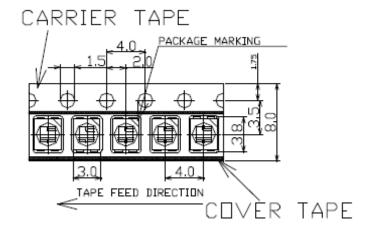
Solder = Lead-Free
Average ramp-up rate = 4℃ / sec. max
Preheat temperature: 150 - 200℃
Preheat time: 120 sec. max.
Ramp-down rate = 6℃ / sec. max.
Peak temperature = 250℃ max.
Time within 5℃ of actual peak temperature = 10 sec .
Duration above 217℃ is 60 sec. max



Reel Dimensions: 7-inch reel



## Carrier Tape Dimensions: Loaded quantity 500 pieces per reel



## Moisture Resistant Packaging

